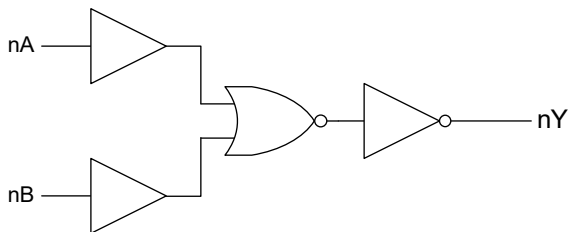


GENERAL DESCRIPTION

The 74AHC32 is a quadruple 2-input positive-OR gate. The supply voltage can range from 2.0V to 5.5V. The device implements the Boolean function $Y = A + B$ or $Y = \overline{A} \times \overline{B}$ in positive logic.

The 74AHC32 is available in Green TSSOP-14, SOIC-14 and TQFN-2.5×3-14L packages. It operates over an ambient temperature range of -40°C to +125°C.

LOGIC DIAGRAM



APPLICATIONS

Industrial Equipment
Medical Devices
Telecom Equipment
Computing Devices

FEATURES

- **Wide Supply Voltage Range: 2.0V to 5.5V**
- **Inputs Accept Voltages Higher than the Supply Voltage and up to 5.5V**
- **+8mA/-8mA Output Current**
- **Low Power Consumption: $I_{CC} = 0.1\mu A$ (TYP)**
- **-40°C to +125°C Operating Temperature Range**
- **Available in Green TSSOP-14, SOIC-14 and TQFN-2.5×3-14L Packages**

FUNCTION TABLE

INPUTS		OUTPUT
nA	nB	nY
H	H	H
L	H	H
H	L	H
L	L	L

H = High Voltage Level
L = Low Voltage Level
X = Don't Care

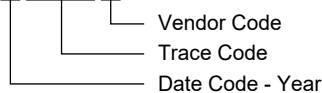
PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
74AHC32	TSSOP-14	-40°C to +125°C	74AHC32XTS14G/TR	74AHC32 XTS14 XXXXX	Tape and Reel, 4000
	SOIC-14	-40°C to +125°C	74AHC32XS14G/TR	74AHC32XS14 XXXXX	Tape and Reel, 2500
	TQFN-2.5x3-14L	-40°C to +125°C	74AHC32XTWB14G/TR	16QTWB XXXXX	Tape and Reel, 10000

MARKING INFORMATION

NOTE: XXXXX = Date Code, Trace Code and Vendor Code.

XXXXX



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{CC} -0.5V to 7.0V
 Input Voltage, V_I ⁽¹⁾ -0.5V to 7.0V
 Output Voltage, V_O ⁽¹⁾ -0.5V to MIN(7.0V, $V_{CC} + 0.5V$)
 Input Clamp Current, I_{IK} ($V_I < 0V$) -20mA
 Output Clamp Current, I_{OK} ($V_O < 0V$ or $V_O > V_{CC}$) $\pm 20mA$
 Continuous Output Current, I_O ($V_O = 0V$ to V_{CC}) $\pm 25mA$
 Continuous Current through V_{CC} or GND $\pm 50mA$
 Junction Temperature ⁽²⁾ +150°C
 Storage Temperature Range -65°C to +150°C
 Lead Temperature (Soldering, 10s) +260°C
 ESD Susceptibility ^{(3) (4)}
 HBM $\pm 6000V$
 CDM $\pm 1000V$

NOTES:

1. The input and output voltage ratings may be exceeded if the input and output clamp current ratings are observed.
2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.
3. For human body model (HBM), all pins comply with ANSI/ESDA/JEDEC JS-001 specifications.
4. For charged device model (CDM), all pins comply with ANSI/ESDA/JEDEC JS-002 specifications.

RECOMMENDED OPERATING CONDITIONS

Supply Voltage, V_{CC} 2.0V to 5.5V
 Input Voltage, V_I 0V to 5.5V
 Output Voltage, V_O 0V to V_{CC}
 Output Current, I_O $\pm 8mA$
 Input Transition Rise or Fall Rate, $\Delta t/\Delta V$
 $V_{CC} = 3.3V \pm 0.3V$ 100ns/V (MAX)
 $V_{CC} = 5V \pm 0.5V$ 20ns/V (MAX)
 Operating Temperature Range -40°C to +125°C

OVERSTRESS CAUTION

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

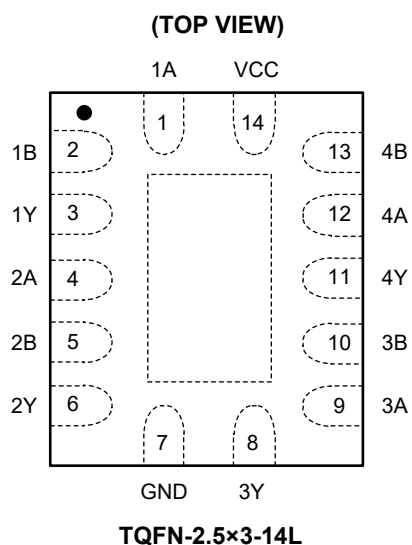
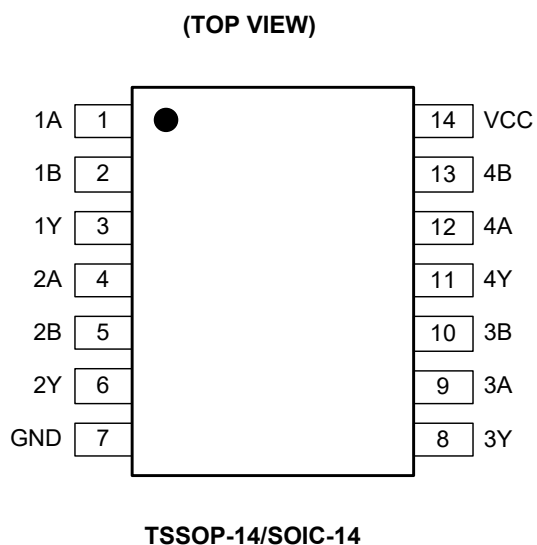
ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

PIN CONFIGURATIONS



PIN DESCRIPTION

PIN		NAME	FUNCTION
TSSOP-14/SOIC-14	TQFN-2.5x3-14L		
1, 4, 9, 12	1, 4, 9, 12	1A, 2A, 3A, 4A	Data Inputs.
2, 5, 10, 13	2, 5, 10, 13	1B, 2B, 3B, 4B	Data Inputs.
3, 6, 8, 11	3, 6, 8, 11	1Y, 2Y, 3Y, 4Y	Data Outputs.
7	7	GND	Ground.
14	14	VCC	Power Supply Pin.

ELECTRICAL CHARACTERISTICS(Full = -40°C to +125°C, all typical values are measured at $T_A = +25^\circ\text{C}$, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
High-Level Input Voltage	V_{IH}	$V_{CC} = 2.0\text{V}$	Full	1.5			V
		$V_{CC} = 3.0\text{V}$	Full	2.1			
		$V_{CC} = 5.5\text{V}$	Full	3.85			
Low-Level Input Voltage	V_{IL}	$V_{CC} = 2.0\text{V}$	Full			0.5	V
		$V_{CC} = 3.0\text{V}$	Full			0.9	
		$V_{CC} = 5.5\text{V}$	Full			1.65	
High-Level Output Voltage	V_{OH}	$V_{CC} = 2.0\text{V}, I_{OH} = -50\mu\text{A}$	Full	1.9	1.99		V
		$V_{CC} = 3.0\text{V}, I_{OH} = -50\mu\text{A}$	Full	2.9	2.99		
		$V_{CC} = 4.5\text{V}, I_{OH} = -50\mu\text{A}$	Full	4.4	4.49		
		$V_{CC} = 3.0\text{V}, I_{OH} = -4\text{mA}$	Full	2.48	2.85		
		$V_{CC} = 4.5\text{V}, I_{OH} = -8\text{mA}$	Full	3.8	4.29		
Low-Level Output Voltage	V_{OL}	$V_{CC} = 2.0\text{V}, I_{OL} = 50\mu\text{A}$	Full		0.01	0.1	V
		$V_{CC} = 3.0\text{V}, I_{OL} = 50\mu\text{A}$	Full		0.01	0.1	
		$V_{CC} = 4.5\text{V}, I_{OL} = 50\mu\text{A}$	Full		0.01	0.1	
		$V_{CC} = 3.0\text{V}, I_{OL} = 4\text{mA}$	Full		0.12	0.5	
		$V_{CC} = 4.5\text{V}, I_{OL} = 8\text{mA}$	Full		0.2	0.5	
Input Leakage Current	I_I	$V_{CC} = 0\text{V to } 5.5\text{V}, V_I = 5.5\text{V or GND}$	Full		± 0.1	± 1	μA
Supply Current	I_{CC}	$V_{CC} = 5.5\text{V}, V_I = V_{CC} \text{ or GND}, I_O = 0\text{A}$	Full		0.1	10	μA
Input Capacitance	C_I	$V_{CC} = 5.0\text{V}, V_I = V_{CC} \text{ or GND}$	+25°C		4		pF

DYNAMIC CHARACTERISTICS(See Figure 1 for test circuit. Full = -40°C to +125°C, all typical values are measured at T_A = +25°C, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		TEMP	MIN ⁽¹⁾	TYP	MAX ⁽¹⁾	UNITS
Low to High Propagation Delay	t _{PLH}	nA or nB to nY, see Figure 2	V _{CC} = 3.0V to 3.6V, C _L = 15pF	Full	0.5	4.5	8.7	ns
			V _{CC} = 3.0V to 3.6V, C _L = 50pF	Full	1.0	6.7	14.1	
			V _{CC} = 4.5V to 5.5V, C _L = 15pF	Full	0.5	3.4	6.0	ns
			V _{CC} = 4.5V to 5.5V, C _L = 50pF	Full	0.5	4.4	8.9	
High to Low Propagation Delay	t _{PHL}		V _{CC} = 3.0V to 3.6V, C _L = 15pF	Full	0.5	5.1	8.2	ns
			V _{CC} = 3.0V to 3.6V, C _L = 50pF	Full	1.0	6.1	10.6	
			V _{CC} = 4.5V to 5.5V, C _L = 15pF	Full	0.5	3.8	6.0	ns
			V _{CC} = 4.5V to 5.5V, C _L = 50pF	Full	0.5	4.5	7.6	
Power Dissipation Capacitance ⁽²⁾	C _{PD}	no load, f = 1MHz	V _{CC} = 5.0V	+25°C		6		pF

NOTES:

- Specified by design and characterization, not production tested.
- C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

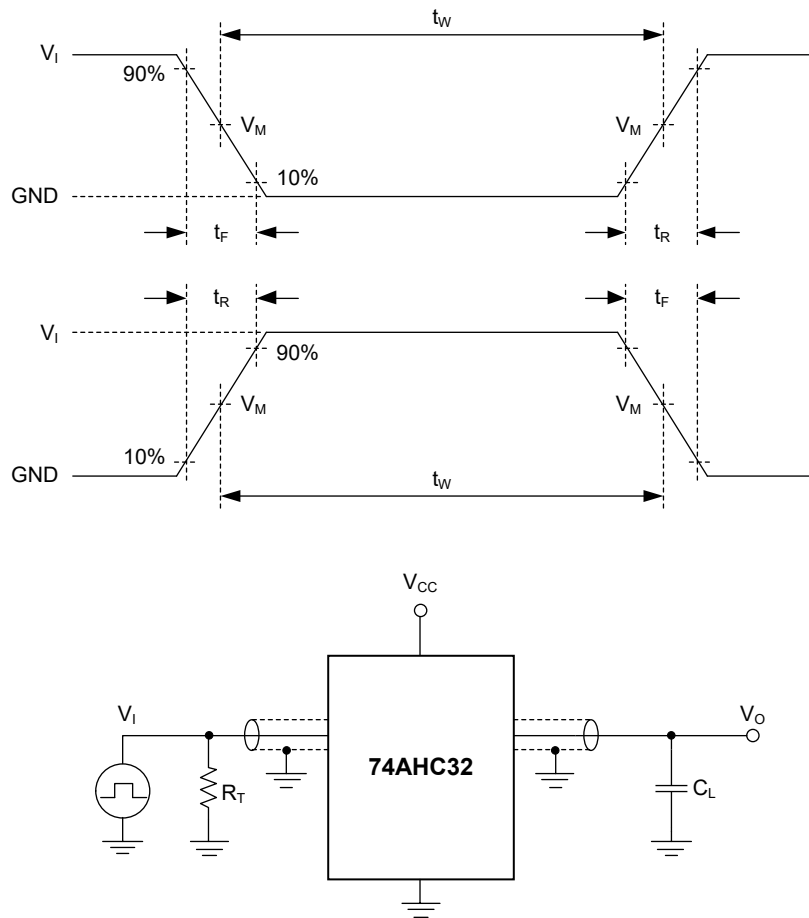
$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$$

where:

f_i = Input frequency in MHz.f_o = Output frequency in MHz.C_L = Output load capacitance in pF.V_{CC} = Supply voltage in Volts.

N = Number of inputs switching.

Σ(C_L × V_{CC}² × f_o) = Sum of the outputs.



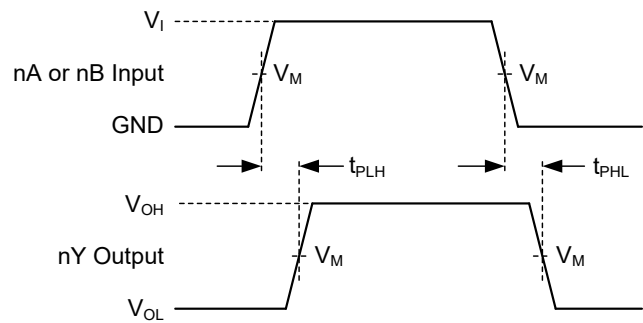
Test conditions are given in Table 1.
Definitions for test circuit:
 C_L : Load capacitance (includes jig and probe).
 R_T : Termination resistance (equals to output impedance Z_O of the pulse generator).

Figure 1. Test Circuit for Measuring Switching Times

Table 1. Test Conditions

SUPPLY VOLTAGE	INPUT		LOAD	TEST
V_{CC}	V_I	t_R, t_F	C_L	
2.0V to 5.5V	V_{CC}	$\leq 3.0\text{ns}$	15pF, 50pF	t_{PHL}, t_{PLH}

WAVEFORMS



Test conditions are given in Table 1.
Measurement points are given in Table 2.
Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Figure 2. Input (nA or nB) to Output (nY) Propagation Delays

SUPPLY VOLTAGE		INPUT		OUTPUT
V_{CC}		V_I	$V_M^{(1)}$	V_M
2.0V to 5.5V		V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$

NOTE:
1. The measurement points should be V_{IH} or V_{IL} when the input rising or falling time exceeds 3.0ns.

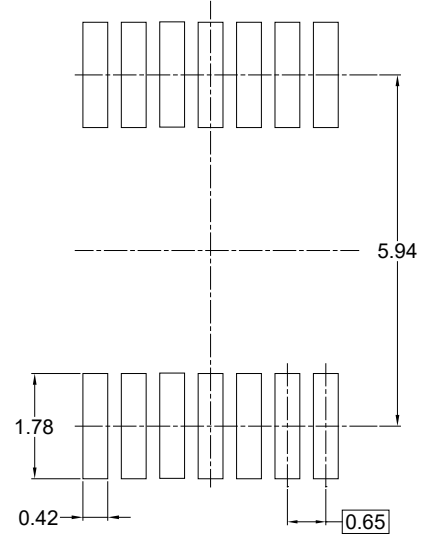
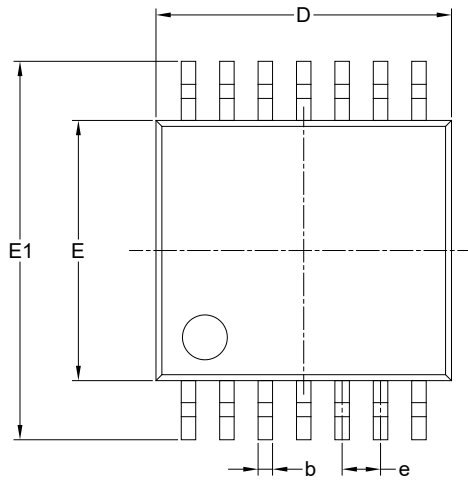
REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

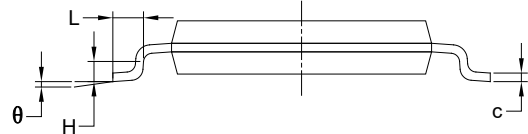
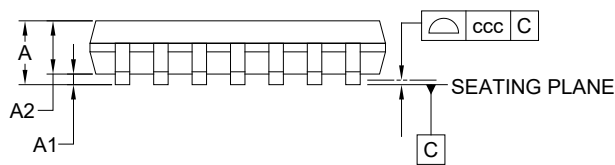
Changes from Original (APRIL 2025) to REV.A	Page
Changed from product preview to production data.....	All

PACKAGE OUTLINE DIMENSIONS

TSSOP-14



RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		
	MIN	NOM	MAX
A	-	-	1.200
A1	0.050	-	0.150
A2	0.800	-	1.050
b	0.190	-	0.300
c	0.090	-	0.200
D	4.860	-	5.100
E	4.300	-	4.500
E1	6.200	-	6.600
e	0.650 BSC		
L	0.450	-	0.750
H	0.250 TYP		
θ	0°	-	8°
ccc	0.100		

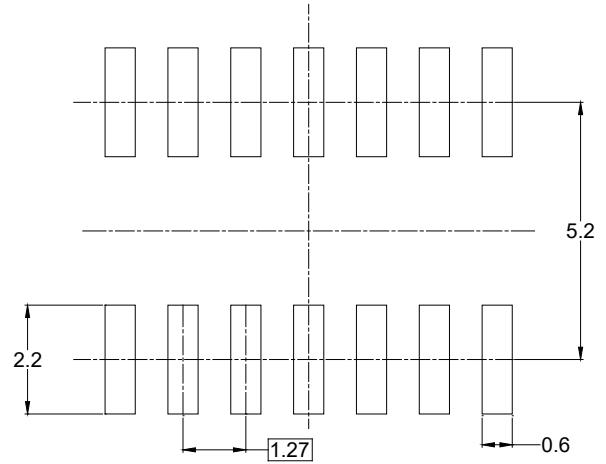
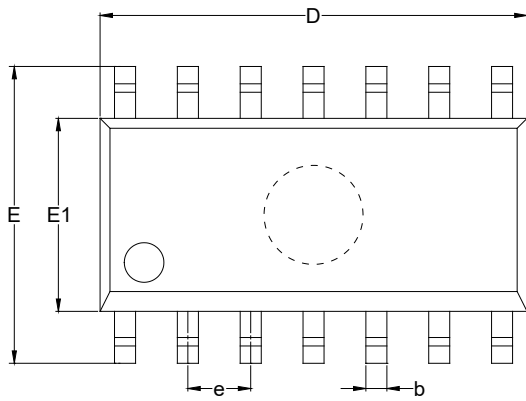
NOTES:

1. This drawing is subject to change without notice.
2. The dimensions do not include mold flashes, protrusions or gate burrs.
3. Reference JEDEC MO-153.

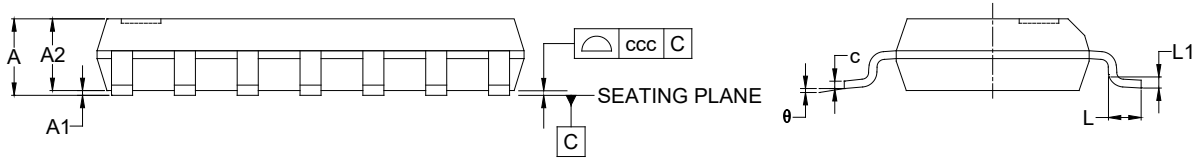
PACKAGE INFORMATION

PACKAGE OUTLINE DIMENSIONS

SOIC-14



RECOMMENDED LAND PATTERN (Unit: mm)



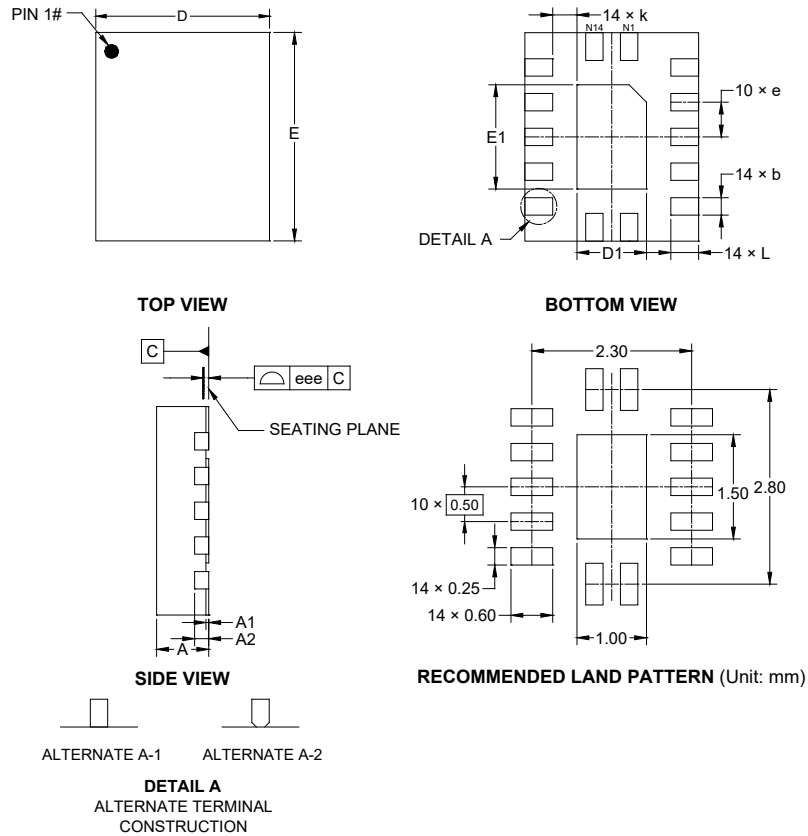
Symbol	Dimensions In Millimeters		
	MIN	NOM	MAX
A	-	-	1.750
A1	0.100	-	0.250
A2	1.250	-	-
b	0.310	-	0.510
c	0.100	-	0.250
D	8.450	-	8.850
E	5.800	-	6.200
E1	3.800	-	4.000
e	1.270 BSC		
L	0.400	-	1.270
L1	0.250 TYP		
θ	0°	-	8°
ccc	0.100		

NOTES:

1. This drawing is subject to change without notice.
2. The dimensions do not include mold flashes, protrusions or gate burrs.
3. Reference JEDEC MS-012.

PACKAGE OUTLINE DIMENSIONS

TQFN-2.5×3-14L



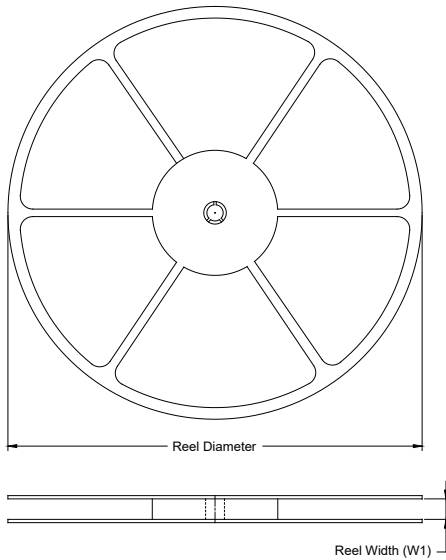
Symbol	Dimensions In Millimeters		
	MIN	NOM	MAX
A	0.700	-	0.800
A1	0.000	-	0.050
A2	0.203 REF		
b	0.200	-	0.300
D	2.400	-	2.600
D1	0.900	-	1.100
E	2.900	-	3.100
E1	1.400	-	1.600
e	0.500 BSC		
k	0.350 REF		
L	0.300	-	0.500
eee	0.080		

NOTE: This drawing is subject to change without notice.

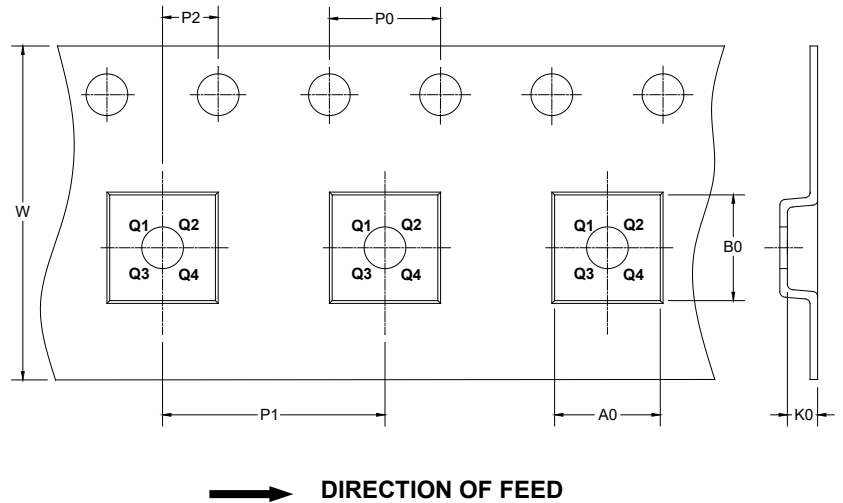
PACKAGE INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

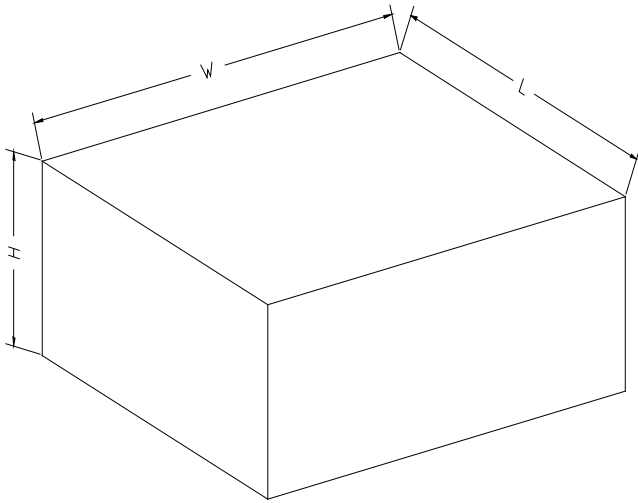
KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TSSOP-14	13"	12.4	6.80	5.40	1.50	4.0	8.0	2.0	12.0	Q1
SOIC-14	13"	16.4	6.60	9.30	2.10	4.0	8.0	2.0	16.0	Q1
TQFN-2.5×3-14L	13"	12.4	2.80	3.30	1.15	4.0	4.0	2.0	12.0	Q1

DD0001

PACKAGE INFORMATION

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13"	386	280	370	5

DD0002